Bruce Technologies 4 Stack Tube Furnace: High temp processing of Si, SiC and Quartz

<table>
<thead>
<tr>
<th>tube</th>
<th>wfr</th>
<th>type</th>
<th>process</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>5”</td>
<td>Atm</td>
<td>Clean Dry ox</td>
</tr>
<tr>
<td>2</td>
<td>5”</td>
<td>Atm</td>
<td>Dry ox, Wet ox</td>
</tr>
<tr>
<td>3</td>
<td>3”</td>
<td>Atm</td>
<td>Wet ox, anneal, Diffusion</td>
</tr>
<tr>
<td>4</td>
<td>4”</td>
<td>Vac</td>
<td>Undoped Poly, LTO</td>
</tr>
</tbody>
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Adixen AMS 100 Deep Reactive Ion Etcher: High aspect ratio etching of Si & SiO₂ wafers

- Fast thru wafer etching of Silicon (10μm/min in most cases)
- Deep Etching of SiO₂ & Pyrex (>30μm,~3KA/min)
- No tooling changes to switch from Si to SiO₂ etching
- 4” wafer handling with adapters for smaller wafers or pieces
- Can etch SiC and Diamond with custom recipes

PlasmaTherm PECVD/RIE PT-700: Industry standard plasma tool for deposition, etching

- PECVD of Amorphous Silicon, SiO₂, Silicon nitride
- Standard RIE and Plasma Etch modes available
- RF(13.56MHz) & LF(50KHz) sources for added flexibility
- Large chucks (~11” dia) for big substrates or multiple pieces

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